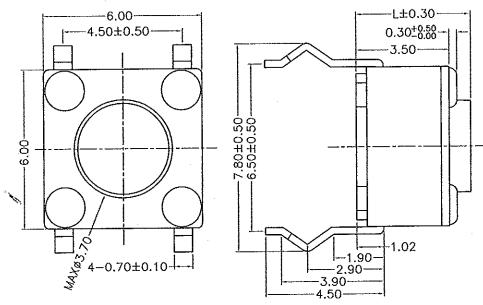
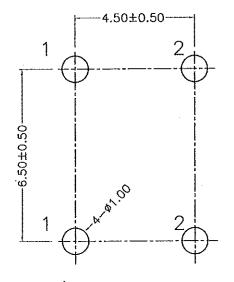
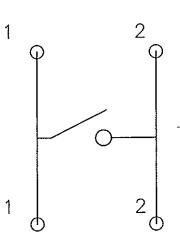
# APPEARANCE DRAWING



MODEL	Ĺ
JTP-1230	4.30
JTP-1230A	5.00
JTP-1230B	9.50
JTP-1230C	8.00
JTP-1230D	13.0
JTP-1230E	7.00





RECOMMEND P.C.B LAYOUT CIRCUIT

未注角度 ±10° 未注公差 0-10mm ±0.3mm 未注公差 10-60mm ±0.5mm

,DRAWN	(LANY)	2-2-2057	MODEL NO	JTP-	12.	30X
CHECKED.	12 7	2-2-2007	SCALE	DRAWING NO	REV	SHEET/OF
APPROVED	Sur Jan	2-2-200)	7:1	TEC-WI-E.WX-184	В3	

產品名稱:	輕觸開關			
Product Name:	TACT SWITCH		•	
型號:	ITP-123x			
Model No.:	JII IZON			·

#### 電器性能 I.

#### ELECTRICAL CHARACTERISTICS

	INICAL CHANACIENISTICS	
1.1	額定電壓 Rated Voltage	12V DC, 50mA
1.2	接觸回路	單通單接觸
	Contact Arrangement	Single Pole, Single Throw
1.3	接觸電阻	以調校於5VDC,10mA之電壓計或調較於
	Contact Resistance	1,000Hz 頻率之電阻表量度測試,接觸電壓應少於
		100mΩ(測試乃以190 gf 力度壓向開關中心點。
		Less than $100 \text{m}\Omega$ when tested by the voltmeter
		method at 5V DC, 10mA, or by an ohmmeter
		allowing a small current at 1,000 Hz.
		(Measurements to be made with a 190 gf load
		applied vertically at the center of the switch.)
1.4	絕緣電阻	≥100MΩ
	Insulation Resistance	\$\frac{1001\text{107}}{2}\$
1.5	耐電壓	250V AC 1 min.
	Dielectric Force	ZUV ACI IIIII.
1.6	開關接點抖動	以每秒鐘3次的速度按動開關,開關在接通和
	Bounce	斷開時的接點抖動時間不大於 10ms。
/ ¥	控	Less than 10m sec (the key shall be struck lightly
1	程部	vertically at its center at a uniform cycling rate
		of 3 operations per second)
$ u arphi$ $\equiv$ .	2月12日 /	

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> 10	1 V	A.D.	032-12-02-2004
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31-01-04	>-2/-04	2-2-04	A/0

### II. 機械性能

#### MECHANICAL CHARACTERISTICS

IANICAL CHARACTERISTIC	
驅動力	□ 160gf ± 30gf
Actuating Force	□ 190gf ± 30gf
	□ 250gf ± 30gf
反彈力	大於 30gf
Return Force	Greater than 30gf
止動力	大於 3Kgf (3 秒)
Stop Strength	Greater than 3Kgf (3 seconds)
行程	0.25 + 0.25 - 0.15
Travel	0.25 + 0.2mm/-0.1mm
動作回路	輕觸式回彈
Arrangement of	Tactile Feedback
Action	Tactile Feedback
操作溫度	
Operating Temp.	-20°C ~ 70°C, R. H. 45~85%
Range	,
貯存溫度	-30°C~80°C;若於-20°C~-30°C及70°C~80°C
Storage Temp. Range	之溫度範圍內持續貯存,則不能多於96小時。
	-30°C ~ 80°C, 96 Hours maximum for
	continuous storage over a range of -20°C ~ -30°C
	and range 70°C ~ 80°C
膠鈕強度	以按動開關的反方向拉,膠鈕強度應在 500gf
Stem Withdrawal	以上。
Force	Greater than 500gf (pulled vertically to the
	opposite direction of stem operation)
	反弾力 Return Force 止動力 Stop Strength 行程 Travel 動作回路 Arrangement of Action 操作温度 Operating Temp. Range 貯存温度 Storage Temp. Range

受 <u>控</u> 工程部

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## III. 壽命及阻抗

### ENDURANCE

3.1 操作壽命	以每秒鐘按動開關兩次,按動 100,000 迴以後,	
Operating Life	(a) 接觸電阻應少於 500mΩ;	
	(b) 開關接觸抖動應少於 20m 秒	
	Following 100,000 Cycles of operation cycling	
	rate (2 operations per second),	
,	(a) Contact Resistance: less than 500mΩ;	
	(b) Bounce: less than 20m sec.	
3.2 濕度抵抗	開關存放於 60℃±2°, 90~95%相對濕度烤爐達	
Moisture Resistance	96 小時,存於室溫及常濕達三十分鐘後,應能	
	達到以下規格:	
	(a) 濕度阻抗:大於 10MΩ;	
	(b) 耐電壓:與1.5項相同;	
	(c) 接觸電阻:與1.3項相同	
	Following exposure to 60°C ±2°C, 90-95%	
	Relative Humidity environment in a test	
	chamber for 96 hours and then, out of the	
	chamber, to room condition of normal	
Ly-y	temperature and humidity for 30 minutes, the	
一 / 受 控 \	requirements set forth below shall be met.	
工程部	(a) Moisture Resistance: Greater than $10M\Omega$ ,	
2004年2月12日	(b) Dielectric Force: Same as section 1.5,	
	(c) Contact Resistance: Same as section 1.3	

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			032-12-02-2004
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31-07-04	2-3-04	70-04	A/0

3.3	高温抵抗	開關貯放於80°C達96小時,然後取出放於室		
	Heat Resistance	温及常濕30分鐘後,應能達到項1及項2的		
		各項規格。		
		Following exposure to an 80°C environment in a		
		test chamber for 96 hours and then, out of the		
		chamber, to room condition of normal		
		temperature and humidity for 30 minutes, the		
		requirements in sections 1 and 2 shall satisfied.		
3.4	低温阻抗	開關貯放於-30°C達96小時,然後取出放於室		
	Resistance to Low	温及常濕30分鐘後,應能達到項1及項2的		
	Temp	各項規格。		
	•	Following exposure to an -30°C environment in		
		a test chamber for 96 hours and then, out of the		
		chamber, to room condition of normal		
		temperature and humidity for 30 minutes, the		
		requirements in sections 1 and 2 shall satisfied.		
3.5	温度循環	65°C,		
	Thermal Cycling			
		ONE		
		-10°C CYCLE		
	and the second s	2H 1H 2H 1H		
	受控\	開關經過五次溫度循環測試(如上圖為一個循		
$\parallel/\parallel$	工程部	環)後,應能達到項1及項2的各項規格。		
الممرة	年2月12日	Following 5 cycles of a thermal cycling test of		
1 Long	THE PRINT	which is prescribed in the diagram above, the		
		requirements in sections 1 & 2 shall be met.		

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31-01-04	7-br-e4	2-2-04	A/0

3.6	衝擊抵抗	根據 MIL-STD-202 方案第 205 條之指示以 30g
	Shock Resistance	之力量衝擊開關,開關應能符合項1及項2之
		各項要求。
		Following application of an impact shock of 30g
		in accordance with the Method 205,
		MIL-STD-202, the requirements in section 2 and
		3 shall be met.
3.7	震動抵抗	根據 MIL-STD-202 方案第 201 條之指示測試開
	Vibration Resistance	關,開關應能符合項1及項2之各項要求,而
		並沒有任何損害及變形。
		Following the test conducted according to the
		Method 201, MIL-STD-202, the switch under test
		shall conform to the requirements of sections 1
		& 2 without any sign of defect both in
		appearance and actuation.

#### IV. 焊錫(以波鋒銲)

SOLDERING (IN CASE THE AUTOMATIC FLOW SOLDERING IS TO BE USED)

4.1	銲錫溫度	不能大於 255°C	
	Soldering Temp.	255°C Max.	
4.2	銲錫時間	持續浸錫時間不能多於5秒	
	Soldering Time	Continuous dipping duration shall not exceed 5	
		seconds.	
4.3	容許上錫次數	不能多於2次,(第2次浸錫時必須待溫度下降	
	Permissible Soldering	至正常温度方可進行。)	
Time		2 times maximum, (twice soldering would be	
控 .		dipped after the temperature goes down to a	
程音		normal temperature)	

如年2月12日

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31-01-04			A/0

4.4	預熱溫度	最大 100℃(必須視乎 PCB 板之可抵抗温度)		
	Preheat Temperature	100°C max (circumferential temperature of the		
		PCB)		
4.5	預熱時間	不能多於 45 秒		
	Preheat Time	45 seconds max.		
4.6	銲劑控制	銲劑應控制至不能滲入裝有原件之 PCB 板上。		
	Flux Streaming	Flux streaming shall be controlled so that it shall		
		not swell beyond the printed wiring board		
		where components are installed.		
4.7	其他注意事項	(a) 銲錫前不應於開關的端子及開關與 PCB		
	Other Precautions	板的接觸面沾上銲劑;		
	•	(b) 開關在銲錫後不宜清洗。		
		(a) Flux shall not be applied on switch		
		terminals and the part mounting surface of		
		the printed wiring board before soldering.		
		(b) Do not wash the switch after soldering		



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Tennifu 31-01-04	List 2-4-04	2-00K	032-12-02-2000 修訂版本 Version No. A/6